

ABSTRACT

The object of the present invention is to provide a resin composition sheet that when used in the manufacture of product packaging such as carrier tapes, and the like, molding temperatures can be lowered from 260-280 °C to 200-250 °C, even when heated to relatively high temperatures using a contact heating device with a mold-releasing film interposed therebetween, wherein poor appearance due to the replication of mold-releasing film features is unlikely to occur. The resin composition sheet relating to one aspect of the present invention comprises polycarbonate resin, amorphous polyester resin, and silicate compound filler. Furthermore, this resin composition sheet is suitable for use in the manufacture of product packaging such as carrier tapes, and the like. Furthermore, when an object that is vulnerable to static electricity is to be accommodated within product packaging, it is preferable to add a conductive filler to prevent the static charge in the accommodated product.